

IN THE CLAIMS:

Please cancel claims 21-26 without prejudice and amend claim 1 such that the claims read as follows:

Claim 1 (currently amended): Support apparatus for an installation of semiconductor processing equipment having a bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline, the support apparatus comprising:

a plurality of support legs; and
a non-rectangular frame disposed on the plurality of support legs, the frame having a frame outline which substantially duplicates the bottom outline of the semiconductor processing equipment, the frame being configured to:

support the installation of semiconductor processing equipment by aligning with the plurality of load-bearing mounting feet of the semiconductor processing equipment; and

provide one or more facilities connection locations that are pre-aligned to one or more facilities connection points of the semiconductor processing equipment, the one or more facilities connection locations adapted to pre-align at least one of a vacuum line, a gas supply line and a fluid supply line to the semiconductor processing equipment prior to installation of the semiconductor processing equipment.

Claim 2 (original): The support apparatus of Claim 1 wherein each of the plurality of support legs is adapted to extend down to a base mount location on underlying flooring.

Claim 3 (original): The support apparatus of Claim 2 wherein the underlying flooring comprises a waffle-grid floor and wherein each base mount location comprises a pad disposed at an interstice of the waffle-grid floor.

Claim 4 (original): The support apparatus of Claim 1 wherein the frame comprises a monolithic frame.

Claim 5 (original): The support apparatus of Claim 4 wherein the monolithic frame comprises a molded steel frame.

Claim 6 (original): The support apparatus of Claim 1 wherein each of the plurality of support legs comprises an adjustable length leg.

Claim 7 (original): The support apparatus of Claim 1 further comprising flanges about the periphery of the frame for supporting raised flooring.

Claim 8 (previously presented): The support apparatus of Claim 1 further comprising flanges along inner edges of the frame to support raised flooring.

Claim 9 (previously presented): The support apparatus of Claim 7 further comprising flanges along inner edges of the frame to support raised flooring.

Claim 10 (original): The support apparatus of Claim 1 further comprising at least one facilities connection locator integrated into the periphery of the frame.

Claim 11 (previously presented): The support apparatus of Claim 10 wherein the at least one facilities connection

locator provides a plurality of connection points for connecting site facilities to the semiconductor processing equipment.

Claim 12 (original): The support apparatus of Claim 11 further comprising gooseneck couplings attached at the plurality of connection points.

Claim 13 (previously presented): The support apparatus of Claim 1 further comprising a plurality of seismic braces each affixed to one of the support legs and adapted to fix to a piece of semiconductor processing equipment to be supported by the support apparatus.

Claims 14-26 (canceled).